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The present invention relates to five other applications filed on the same date: A Method and System for Monitoring and Profiling an Integrated Circuit Die Temperature (Atty. Docket: SMQ-087/P6548), An Integrated Temperature Sensor (Atty. Docket: SMQ-088/P6549), Quantifying a Difference Between Nodal Voltages (Atty. Docket: 03226.116001/P6348), Low Voltage Temperature Independent and Temperature Dependent Voltage Generator (Atty. Docket: 03226.112001/P6322) and Temperature Calibration Using On-Chip Electrical Fuses (Atty. Docket: 03226.108001/P6216).

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